
Semiconductor devices - Mechanical and climatic test methods - Part 23: High temperature operating life (IEC 60749-23:2004)

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EUROPEAN STANDARD

EN 60749-23

NORME EUROPÉENNE

EUROPÄISCHE NORM

April 2004

ICS 31.080.01

English version

**Semiconductor devices –
Mechanical and climatic test methods
Part 23: High temperature operating life
(IEC 60749-23:2004)**

Dispositifs à semiconducteurs –
Méthodes d'essais mécaniques
et climatiques
Partie 23: Durée de vie en
fonctionnement à haute température
(CEI 60749-23:2004)

Halbleiterbauelemente –
Mechanische und klimatische
Prüfverfahren
Teil 23: Lebensdauer bei hoher
Temperatur
(IEC 60749-23:2004)

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Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

The text of document 47/1735/FDIS, future edition 1 of IEC 60749-23, prepared by IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60749-23 on 2004-04-01.

The following dates were fixed:

- latest date by which the EN has to be implemented
at national level by publication of an identical
national standard or by endorsement (dop) 2005-01-01
- latest date by which the national standards conflicting
with the EN have to be withdrawn (dow) 2007-04-01

Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 60749-23:2004 was approved by CENELEC as a European Standard without any modification.

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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE Where an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60747	Series	Semiconductor devices – Discrete devices and integrated circuits	EN 60747	Series
IEC 60749-34	- 1)	Semiconductor devices - Mechanical and climatic test methods Part 34: Power cycling	EN 60749-34	2004 2)

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1) Undated reference.

2) Valid edition at date of issue.

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2004-02

**Dispositifs à semiconducteurs –
Méthodes d'essais mécaniques et climatiques –**

**Partie 23:
Durée de vie en fonctionnement
à haute température**

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**Semiconductor devices –
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**Part 23:
High temperature operating life**

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Commission Electrotechnique Internationale
International Electrotechnical Commission
Международная Электротехническая Комиссия

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR DEVICES –
MECHANICAL AND CLIMATIC TEST METHODS –**

Part 23: High temperature operating life

FOREWORD

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International Standard IEC 60749-23 has been prepared by IEC technical committee 47: Semiconductor devices.

This first edition is based on the IEC/PAS 62189 (2000).

The text of this standard is based on the following documents:

FDIS	Report on voting
47/1735/FDIS	47/1745/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.